S 1

S 2

S 3

G

4



## N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)			
40	0.012 at V <sub>GS</sub> = 10 V	12	15 nC			
	0.012 at V <sub>GS</sub> = 4.5 V	9	10110			

8 D

6

5

7 D

D

D

SO-8

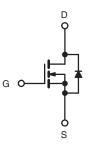
Top View



- Halogen-free According to IEC 61249-2-21
   Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested
- Compliant to RoHS directive 2002/95/EC

#### **APPLICATIONS**

- Synchronous Rectification
- POL, IBC
- Secondary Side



N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	40	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		
	T <sub>C</sub> = 25 °C		12		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 70 °C		8		
Commuous Drain Current $(T_{\rm J} = 150^{\circ} {\rm C})$	T <sub>A</sub> = 25 °C	- I <sub>D</sub> -	12.4 <sup>a, b</sup>	Α	
	T <sub>A</sub> = 70 °C		8.8 <sup>a, b</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	50		
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	15		
Avalanche Energy		E <sub>AS</sub>	11	mJ	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		5	Α	
	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.1 <sup>a, b</sup>	A	
	T <sub>C</sub> = 25 °C		6		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C		3.8	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5 <sup>a, b</sup>	vv	
	T <sub>A</sub> = 70 °C	1 1	1.6 <sup>a, b</sup>		
Operating Junction and Storage Temperatur	T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	37	50	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	17	21	0/11		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85  $^{\circ}\text{C/W}.$ 

d. Based on T<sub>C</sub> = 25 °C.



<b>SPECIFICATIONS</b> $T_J = 25 \text{ °C}$ ,	L			-			
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					1		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	40			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		40		- mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 6			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	1		3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40 V, V_{GS} = 0 V$			1	- μΑ	
	-033	$V_{DS}$ = 40 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C			5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5$ V, $V_{GS}$ = 10 V	50			A	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12.4 A	0.010			Ω	
	· ·DS(on)	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10.8 \text{ A}$		0.012		52	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 12.4 A		56		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			2000		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz		260			
Reverse Transfer Capacitance	C <sub>rss</sub>			150			
Tabal Oaks Observe	0	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 12.4 \text{ A}$		33	50		
Total Gate Charge	Qg			15	23	nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 12.4 A		6.7			
Gate-Drain Charge	Q <sub>gd</sub>			5.1			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			25	40		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 20 V, $R_L$ = 2 $\Omega$		12	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	${ m I}_{ m D}\cong$ 10 A, ${ m V}_{ m GEN}$ = 4.5 V, ${ m R}_{ m g}$ = 1 $\Omega$		25	40		
Fall Time	t <sub>f</sub>			10	15		
Turn-On Delay Time	t <sub>d(on)</sub>			10	15	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, \text{ R}_{1} = 2 \Omega$		15	25	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		30	45		
Fall Time	t <sub>f</sub>			10	15		
Drain-Source Body Diode Characteristi	cs		I.			1	
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			30		
Pulse Diode Forward Current	I <sub>SM</sub>			1	50	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 10 A, V <sub>GS</sub> = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			30	60	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			26	52	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	I <sub>F</sub> = 10 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		17.5			
Reverse Recovery Rise Time	t <sub>b</sub>	—		12.5		ns	

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %

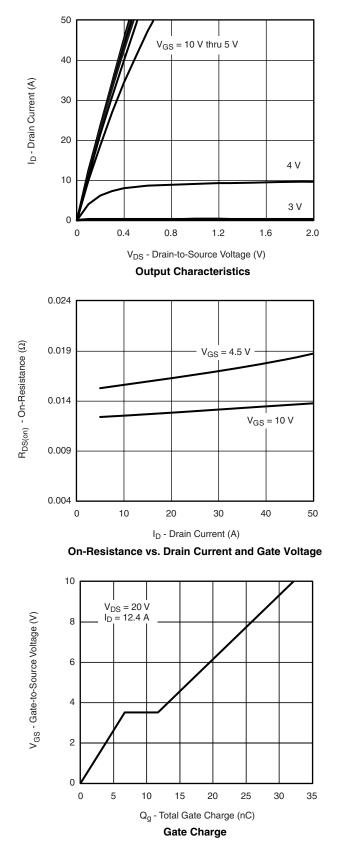
b. Guaranteed by design, not subject to production testing.

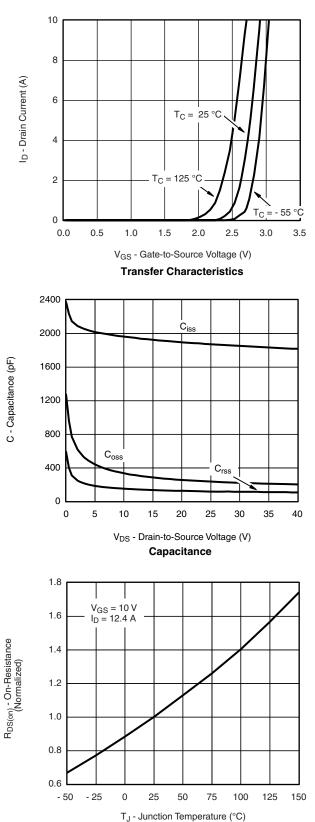
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

emi



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

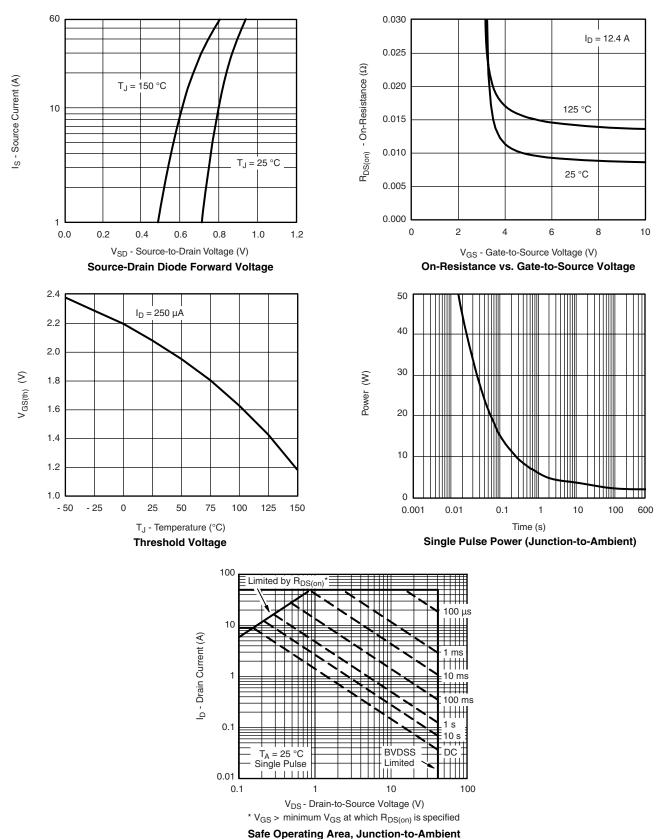




**On-Resistance vs. Junction Temperature** 

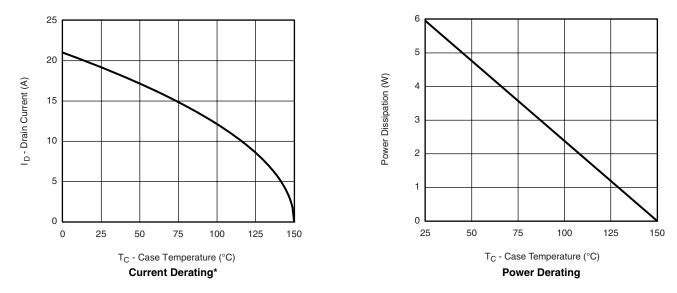


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



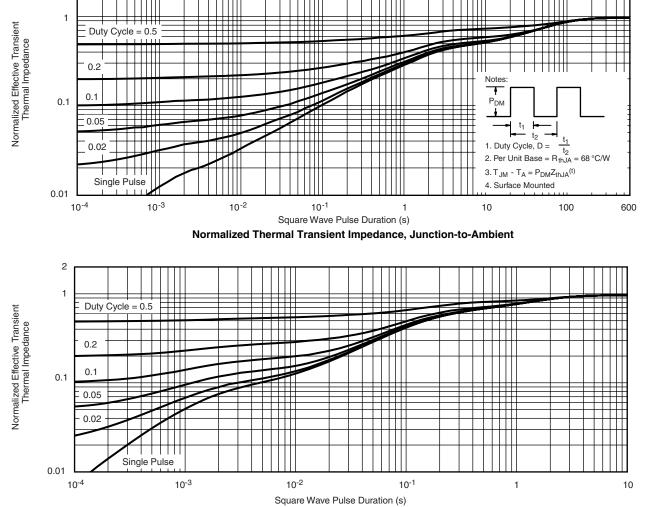


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

2



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

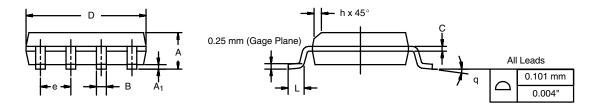
Normalized Thermal Transient Impedance, Junction-to-Foot





# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

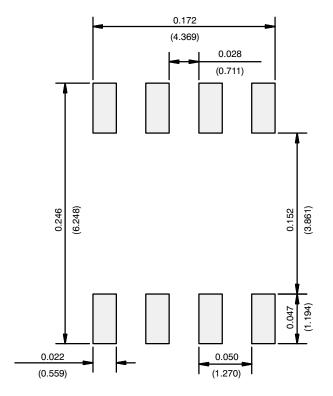




	MILLIM	ETERS	INCHES		
DIM	Min	Max	Min	Max	
A	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	<b>8</b> °	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)



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